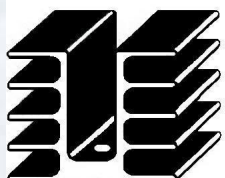


# HALA CLIPS THERMAL MANAGEMENT

CREATING CLOSEST CONTACT



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# HALA CLIPS THERMAL MANAGEMENT



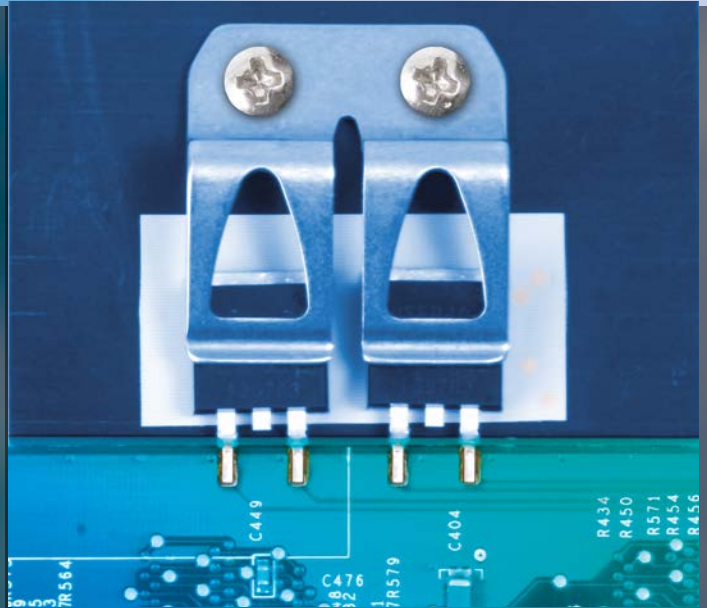
CREATING CLOSEST CONTACT

### BENEFITS

- ▣ Maximized thermal contact (even at minimum package height)
- ▣ FE-simulation optimised stress behaviour
- ▣ Optimized interaction with HALA Thermal Interface Materials
- ▣ Mounting friendly design
- ▣ Easy chip identification by apertures

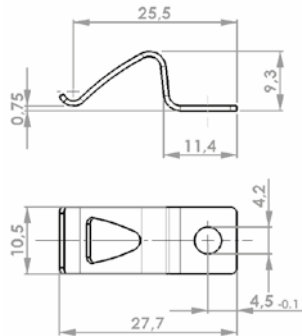
We design your tailor-made clip solution.

Please contact us as your development partner.



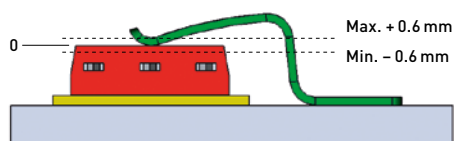
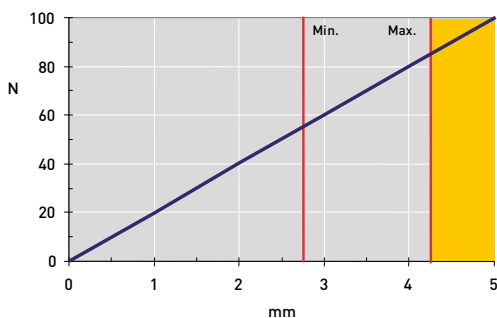
### HALA CLIP TO 220-1

#### Dimensions



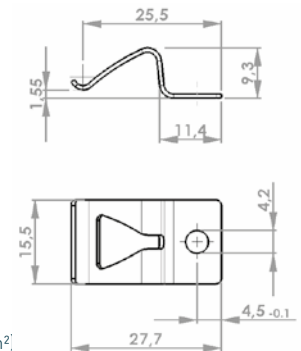
- ▣ Force range: ca. 55...85 N
- ▣ Pressure range: ca. 35...55 N/cm<sup>2</sup> (50...80 PSI) for different types of TO 220 packages (Surface area TO 220 approx. 1.6 cm<sup>2</sup>)

### FORCE VS. DEFLECTION



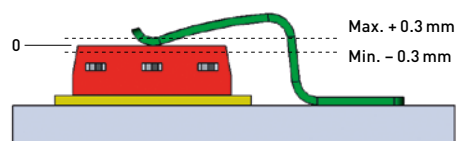
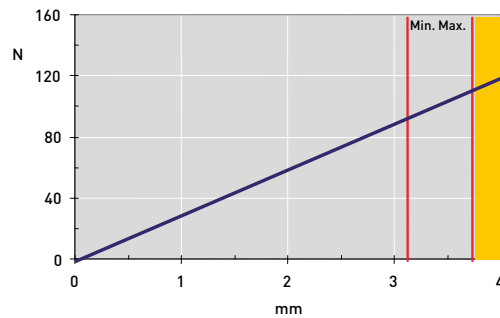
### HALA CLIP TO 247-1

#### Dimensions



- ▣ Force range: ca. 95...110 N
- ▣ Pressure range: ca. 28...32 N/cm<sup>2</sup> (40...47 PSI) for different types of TO 247 packages (Surface area TO 247 approx. 3.4 cm<sup>2</sup>)

### FORCE VS. DEFLECTION



All technical data and information are without warranty and believed to be reliable and accurate. Since the products are not provided to conform with mutually agreed specifications and their use and processing. Release 9/2014 are unknown we cannot guarantee results, freedom from patent infringement, or their suitability for any application. Product testing by the applicant is recommended. We reserve the right of changes.